

Invisipin® Board to Board

Fully Customizable
High Speed Interconnect

Invisipin® Board to Board Interposers are highly customizable, high performance electrical interconnect solutions for use in board to board or board to module applications. Invisipin® Board to Board Interposers consist of engineered to print conductive elastomer pin arrays and integrated compression limiters. Interconnect patterns are infinitely configurable so mixed digital, power, and RF signals can be connected using the same interposer. Invisipin® Board to Board's extremely short signal path, low resistance, as well as ultra-low inductance allows a high performance connection.

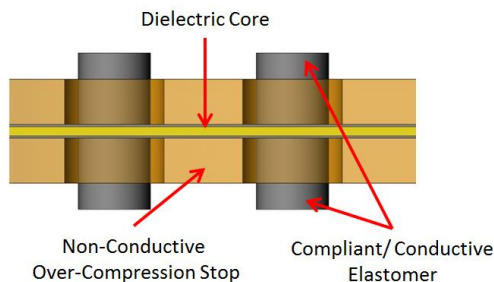
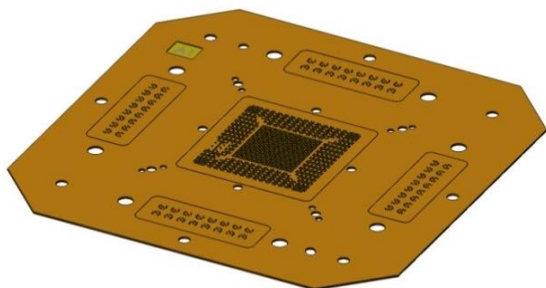
SPECIFICATIONS

Contact Pitch Sizes	0.3mm, 0.4mm, 0.5mm, 0.65mm, 0.8mm, 1.0mm*
Bandwidth	< -1 dB through 65 GHz
Current Carrying Capabilities	1 - 4 Amps/pin
Contact DC Resistance	10 - 50 mΩ
Environmental	-40°C to +150°C
Self Inductance	0.28nH – 0.72nH
Mutual Inductance	0.24nH – 0.64nH
Typical Contact Force	10 – 35 grams/pin
Contact Compliance	100 μm – 400 μm

*Note: Custom pitches and patterns are available.

INTERPOSER CONSTRUCTION

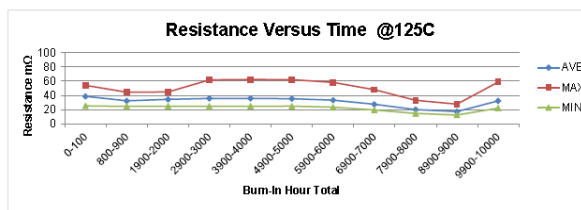
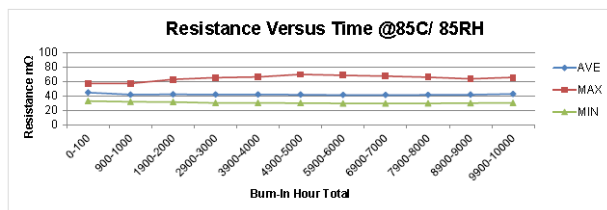
Invisipin® Board to Board Interposer



Invisipin® Board to Board Interposers are made using low outgassing conductive silicone elastomer in conjunction with highly stable cores.

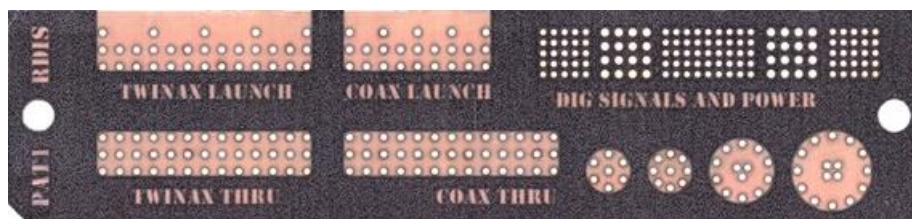
HIGH RELIABILITY

Burn-In – 10,000hrs – Pulsed DC 1A/ 1kHz/ 10% Duty Cycle



HIGHLY CUSTOMIZABLE

Mixed Digital, Power, RF on Same Interposer



R&D INTERCONNECT SOLUTIONS

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